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Applications of "Embedded - Microcontrollers"

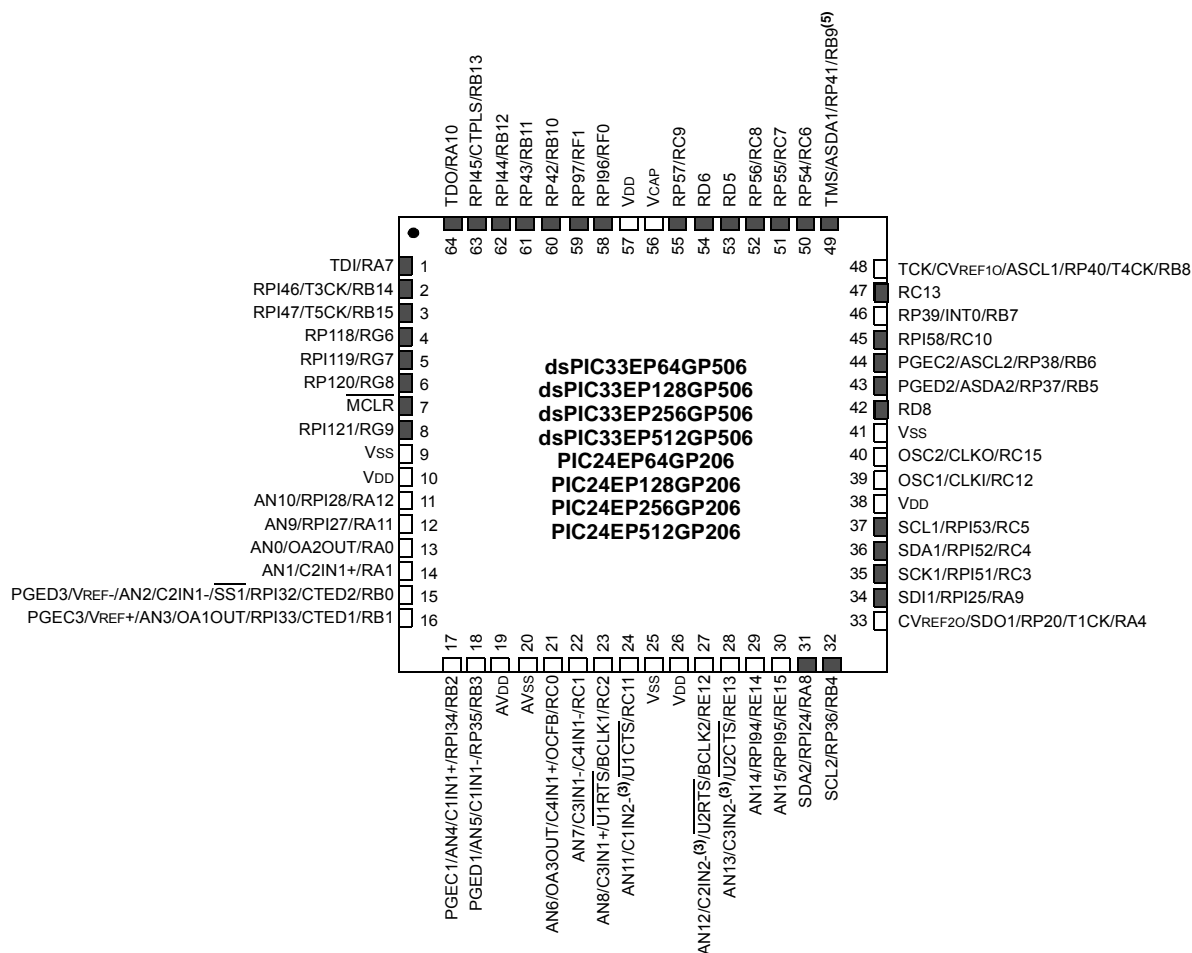| Details	
Product Status	Active
Core Processor	PIC
Core Size	16-Bit
Speed	60 MIPs
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	53
Program Memory Size	64KB (22K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	4K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 16x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	64-VFQFN Exposed Pad
Supplier Device Package	64-VQFN (9x9)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24ep64gp206-e-mr

Pin Diagrams (Continued)

64-Pin QFN[1,2,3,4]

☐ = Pins are up to 5V tolerant

Top pins (64–49), left to right:
TDO/RA10 (64), RPI45/CTPLS/RB13 (63), RPI44/RB12 (62), RP43/RB11 (61), RP42/RB10 (60), RP97/RF1 (59), RPI96/RF0 (58), VDD (57), VCAP (56), RP57/RC9 (55), RD6 (54), RD5 (53), RP56/RC8 (52), RP55/RC7 (51), RP54/RC6 (50), TMS/ASDA1/RP41/RB9[5] (49)

Left pins (1–16):
1 TDI/RA7
2 RPI46/T3CK/RB14
3 RPI47/T5CK/RB15
4 RP118/RG6
5 RPI119/RG7
6 RP120/RG8
7 MCLR
8 RPI121/RG9
9 VSS
10 VDD
11 AN10/RPI28/RA12
12 AN9/RPI27/RA11
13 AN0/OA2OUT/RA0
14 AN1/C2IN1+/RA1
15 PGED3/VREF-/AN2/C2IN1-/SS1/RPI32/CTED2/RB0
16 PGEC3/VREF+/AN3/OA1OUT/RPI33/CTED1/RB1

Center device labels:
dsPIC33EP64GP506
dsPIC33EP128GP506
dsPIC33EP256GP506
dsPIC33EP512GP506
PIC24EP64GP206
PIC24EP128GP206
PIC24EP256GP206
PIC24EP512GP206

Right pins (48–33):
48 TCK/CVREF1O/ASCL1/RP40/T4CK/RB8
47 RC13
46 RP39/INT0/RB7
45 RPI58/RC10
44 PGEC2/ASCL2/RP38/RB6
43 PGED2/ASDA2/RP37/RB5
42 RD8
41 VSS
40 OSC2/CLKO/RC15
39 OSC1/CLKI/RC12
38 VDD
37 SCL1/RPI53/RC5
36 SDA1/RPI52/RC4
35 SCK1/RPI51/RC3
34 SDI1/RPI25/RA9
33 CVREF2O/SDO1/RP20/T1CK/RA4

Bottom pins (17–32), left to right:
17 PGEC1/AN4/C1IN1+/RPI34/RB2
18 PGED1/AN5/C1IN1-/RP35/RB3
19 AVDD
20 AVSS
21 AN6/OA3OUT/C4IN1+/RC0
22 AN7/C3IN1-/C4IN1-/RC1
23 AN8/C3IN1+/U1RTS/BCLK1/RC2
24 AN11/C1IN2-/U1CTS/RC11
25 VSS
26 VDD
27 AN12/C2IN2-/U2RTS/BCLK2/RE12
28 AN13/C3IN2-/U2CTS/RE13
29 AN14/RPI94/RE14
30 AN15/RPI95/RE15
31 SDA2/RPI24/RA8
32 SCL2/RP36/RB4

Note 1: The RPn/RPIn pins can be used by any remappable peripheral with some limitation. See **Section 11.4 "Peripheral Pin Select (PPS)"** for available peripherals and for information on limitations.

2: Every I/O port pin (RAx-RGx) can be used as a Change Notification pin (CNAx-CNGx). See **Section 11.0 "I/O Ports"** for more information.

3: This pin is not available as an input when OPMODE (CMxCON<10>) = 1.

4: The metal pad at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.

5: There is an internal pull-up resistor connected to the TMS pin when the JTAG interface is active. See the JTAGEN bit field in Table 27-2.

TABLE 1-1: PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name[4]	Pin Type	Buffer Type	PPS	Description
C1IN1-	I	Analog	No	Op Amp/Comparator 1 Negative Input 1.
C1IN2-	I	Analog	No	Comparator 1 Negative Input 2.
C1IN1+	I	Analog	No	Op Amp/Comparator 1 Positive Input 1.
OA1OUT	O	Analog	No	Op Amp 1 output.
C1OUT	O	—	Yes	Comparator 1 output.
C2IN1-	I	Analog	No	Op Amp/Comparator 2 Negative Input 1.
C2IN2-	I	Analog	No	Comparator 2 Negative Input 2.
C2IN1+	I	Analog	No	Op Amp/Comparator 2 Positive Input 1.
OA2OUT	O	Analog	No	Op Amp 2 output.
C2OUT	O	—	Yes	Comparator 2 output.
C3IN1-	I	Analog	No	Op Amp/Comparator 3 Negative Input 1.
C3IN2-	I	Analog	No	Comparator 3 Negative Input 2.
C3IN1+	I	Analog	No	Op Amp/Comparator 3 Positive Input 1.
OA3OUT	O	Analog	No	Op Amp 3 output.
C3OUT	O	—	Yes	Comparator 3 output.
C4IN1-	I	Analog	No	Comparator 4 Negative Input 1.
C4IN1+	I	Analog	No	Comparator 4 Positive Input 1.
C4OUT	O	—	Yes	Comparator 4 output.
CVREF1O	O	Analog	No	Op amp/comparator voltage reference output.
CVREF2O	O	Analog	No	Op amp/comparator voltage reference divided by 2 output.
PGED1	I/O	ST	No	Data I/O pin for Programming/Debugging Communication Channel 1.
PGEC1	I	ST	No	Clock input pin for Programming/Debugging Communication Channel 1.
PGED2	I/O	ST	No	Data I/O pin for Programming/Debugging Communication Channel 2.
PGEC2	I	ST	No	Clock input pin for Programming/Debugging Communication Channel 2.
PGED3	I/O	ST	No	Data I/O pin for Programming/Debugging Communication Channel 3.
PGEC3	I	ST	No	Clock input pin for Programming/Debugging Communication Channel 3.
$\overline{\text{MCLR}}$	I/P	ST	No	Master Clear (Reset) input. This pin is an active-low Reset to the device.
AVDD	P	P	No	Positive supply for analog modules. This pin must be connected at all times.
AVSS	P	P	No	Ground reference for analog modules. This pin must be connected at all times.
VDD	P	—	No	Positive supply for peripheral logic and I/O pins.
VCAP	P	—	No	CPU logic filter capacitor connection.
VSS	P	—	No	Ground reference for logic and I/O pins.
VREF+	I	Analog	No	Analog voltage reference (high) input.
VREF-	I	Analog	No	Analog voltage reference (low) input.

Legend: CMOS = CMOS compatible input or output   Analog = Analog input   P = Power
ST = Schmitt Trigger input with CMOS levels   O = Output   I = Input
PPS = Peripheral Pin Select   TTL = TTL input buffer

Note 1: This pin is available on dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices only.

2: This pin is available on dsPIC33EPXXXGP/MC50X devices only.

3: This is the default Fault on Reset for dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices. See **Section 16.0 "High-Speed PWM Module (dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X Devices Only)"** for more information.

4: Not all pins are available in all packages variants. See the **"Pin Diagrams"** section for pin availability.

5: There is an internal pull-up resistor connected to the TMS pin when the JTAG interface is active. See the JTAGEN bit field in Table 27-2.

2.0 GUIDELINES FOR GETTING STARTED WITH 16-BIT DIGITAL SIGNAL CONTROLLERS AND MICROCONTROLLERS

Note 1: This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to the related section of the "*dsPIC33/PIC24 Family Reference Manual*", which is available from the Microchip web site (www.microchip.com)

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

2.1 Basic Connection Requirements

Getting started with the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families requires attention to a minimal set of device pin connections before proceeding with development. The following is a list of pin names, which must always be connected:

- All VDD and VSS pins
(see **Section 2.2 "Decoupling Capacitors"**)
- All AVDD and AVSS pins (regardless if ADC module is not used)
(see **Section 2.2 "Decoupling Capacitors"**)
- VCAP
(see **Section 2.3 "CPU Logic Filter Capacitor Connection (VCAP)"**)
- MCLR pin
(see **Section 2.4 "Master Clear (MCLR) Pin"**)
- PGECx/PGEDx pins used for In-Circuit Serial Programming™ (ICSP™) and debugging purposes
(see **Section 2.5 "ICSP Pins"**)
- OSC1 and OSC2 pins when external oscillator source is used
(see **Section 2.6 "External Oscillator Pins"**)

Additionally, the following pins may be required:

- VREF+/VREF- pins are used when external voltage reference for the ADC module is implemented

Note: The AVDD and AVSS pins must be connected, independent of the ADC voltage reference source.

2.2 Decoupling Capacitors

The use of decoupling capacitors on every pair of power supply pins, such as VDD, VSS, AVDD and AVSS is required.

Consider the following criteria when using decoupling capacitors:

- **Value and type of capacitor:** Recommendation of 0.1 µF (100 nF), 10-20V. This capacitor should be a low-ESR and have resonance frequency in the range of 20 MHz and higher. It is recommended to use ceramic capacitors.
- **Placement on the printed circuit board:** The decoupling capacitors should be placed as close to the pins as possible. It is recommended to place the capacitors on the same side of the board as the device. If space is constricted, the capacitor can be placed on another layer on the PCB using a via; however, ensure that the trace length from the pin to the capacitor is within one-quarter inch (6 mm) in length.
- **Handling high-frequency noise:** If the board is experiencing high-frequency noise, above tens of MHz, add a second ceramic-type capacitor in parallel to the above described decoupling capacitor. The value of the second capacitor can be in the range of 0.01 µF to 0.001 µF. Place this second capacitor next to the primary decoupling capacitor. In high-speed circuit designs, consider implementing a decade pair of capacitances as close to the power and ground pins as possible. For example, 0.1 µF in parallel with 0.001 µF.
- **Maximizing performance:** On the board layout from the power supply circuit, run the power and return traces to the decoupling capacitors first, and then to the device pins. This ensures that the decoupling capacitors are first in the power chain. Equally important is to keep the trace length between the capacitor and the power pins to a minimum, thereby reducing PCB track inductance.

3.7 CPU Control Registers

REGISTER 3-1: SR: CPU STATUS REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/C-0	R/C-0	R-0	R/W-0
OA[1]	OB[1]	SA[1,4]	SB[1,4]	OAB[1]	SAB[1]	DA[1]	DC
bit 15							bit 8

R/W-0[2,3]	R/W-0[2,3]	R/W-0[2,3]	R-0	R/W-0	R/W-0	R/W-0	R/W-0
IPL2	IPL1	IPL0	RA	N	OV	Z	C
bit 7							bit 0

Legend:		C = Clearable bit	
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1'= Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15   **OA:** Accumulator A Overflow Status bit[1]

     1 = Accumulator A has overflowed
     0 = Accumulator A has not overflowed

bit 14   **OB:** Accumulator B Overflow Status bit[1]

     1 = Accumulator B has overflowed
     0 = Accumulator B has not overflowed

bit 13   **SA:** Accumulator A Saturation 'Sticky' Status bit[1,4]

     1 = Accumulator A is saturated or has been saturated at some time
     0 = Accumulator A is not saturated

bit 12   **SB:** Accumulator B Saturation 'Sticky' Status bit[1,4]

     1 = Accumulator B is saturated or has been saturated at some time
     0 = Accumulator B is not saturated

bit 11   **OAB:** OA || OB Combined Accumulator Overflow Status bit[1]

     1 = Accumulators A or B have overflowed
     0 = Neither Accumulators A or B have overflowed

bit 10   **SAB:** SA || SB Combined Accumulator 'Sticky' Status bit[1]

     1 = Accumulators A or B are saturated or have been saturated at some time
     0 = Neither Accumulators A or B are saturated

bit 9   **DA:** DO Loop Active bit[1]

     1 = DO loop is in progress
     0 = DO loop is not in progress

bit 8   **DC:** MCU ALU Half Carry/$\overline{\text{Borrow}}$ bit

     1 = A carry-out from the 4th low-order bit (for byte-sized data) or 8th low-order bit (for word-sized data) of the result occurred
     0 = No carry-out from the 4th low-order bit (for byte-sized data) or 8th low-order bit (for word-sized data) of the result occurred

Note 1:   This bit is available on dsPIC33EPXXXMC20X/50X and dsPIC33EPXXXGP50X devices only.

     2:   The IPL<2:0> bits are concatenated with the IPL<3> bit (CORCON<3>) to form the CPU Interrupt Priority Level. The value in parentheses indicates the IPL, if IPL<3> = 1. User interrupts are disabled when IPL<3> = 1.

     3:   The IPL<2:0> Status bits are read-only when the NSTDIS bit (INTCON1<15>) = 1.

     4:   A data write to the SR register can modify the SA and SB bits by either a data write to SA and SB or by clearing the SAB bit. To avoid a possible SA or SB bit write race condition, the SA and SB bits should not be modified using bit operations.

4.0   MEMORY ORGANIZATION

Note:	This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"Program Memory"** (DS70613) in the "*dsPIC33/PIC24 Family Reference Manual*", which is available from the Microchip web site (www.microchip.com).

The dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X architecture features separate program and data memory spaces, and buses. This architecture also allows the direct access of program memory from the Data Space (DS) during code execution.

4.1   Program Address Space

The program address memory space of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices is 4M instructions. The space is addressable by a 24-bit value derived either from the 23-bit PC during program execution, or from table operation or Data Space remapping, as described in **Section 4.8 "Interfacing Program and Data Memory Spaces"**.

User application access to the program memory space is restricted to the lower half of the address range (0x000000 to 0x7FFFFF). The exception is the use of TBLRD operations, which use TBLPAG<7> to read Device ID sections of the configuration memory space.

The program memory maps, which are presented by device family and memory size, are shown in Figure 4-1 through Figure 4-5.

FIGURE 4-1:   PROGRAM MEMORY MAP FOR dsPIC33EP32GP50X, dsPIC33EP32MC20X/50X AND PIC24EP32GP/MC20X DEVICES

Note: Memory areas are not shown to scale.
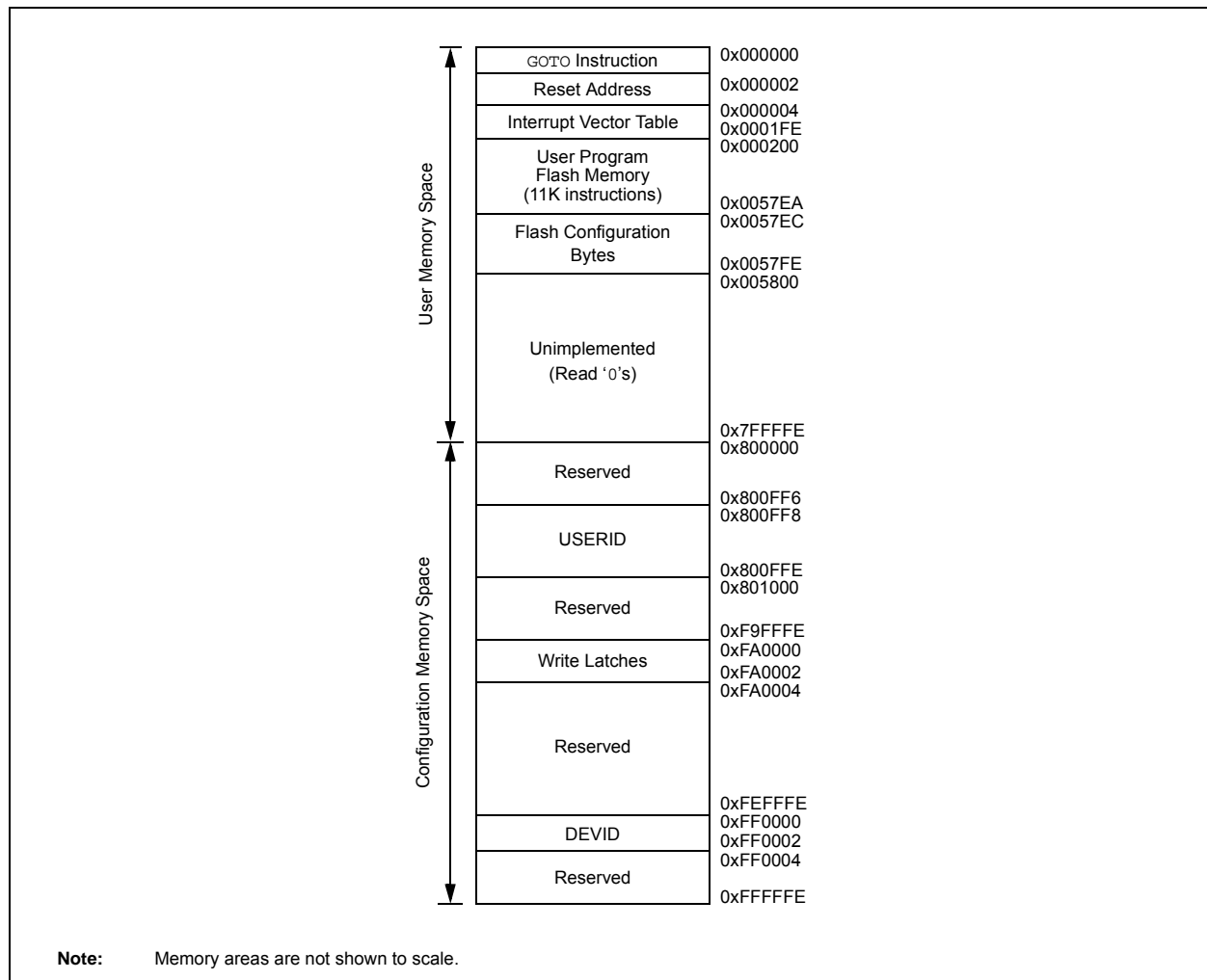
TABLE 4-20: ADC1 REGISTER MAP

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
ADC1BUF0	0300	ADC1 Data Buffer 0																xxxx
ADC1BUF1	0302	ADC1 Data Buffer 1																xxxx
ADC1BUF2	0304	ADC1 Data Buffer 2																xxxx
ADC1BUF3	0306	ADC1 Data Buffer 3																xxxx
ADC1BUF4	0308	ADC1 Data Buffer 4																xxxx
ADC1BUF5	030A	ADC1 Data Buffer 5																xxxx
ADC1BUF6	030C	ADC1 Data Buffer 6																xxxx
ADC1BUF7	030E	ADC1 Data Buffer 7																xxxx
ADC1BUF8	0310	ADC1 Data Buffer 8																xxxx
ADC1BUF9	0312	ADC1 Data Buffer 9																xxxx
ADC1BUFA	0314	ADC1 Data Buffer 10																xxxx
ADC1BUFB	0316	ADC1 Data Buffer 11																xxxx
ADC1BUFC	0318	ADC1 Data Buffer 12																xxxx
ADC1BUFD	031A	ADC1 Data Buffer 13																xxxx
ADC1BUFE	031C	ADC1 Data Buffer 14																xxxx
ADC1BUFF	031E	ADC1 Data Buffer 15																xxxx
AD1CON1	0320	ADON	—	ADSIDL	ADDMABM	—	AD12B	FORM<1:0>		SSRC<2:0>			SSRCG	SIMSAM	ASAM	SAMP	DONE	0000
AD1CON2	0322	VCFG<2:0>			—	—	CSCNA	CHPS<1:0>		BUFS	SMPI<4:0>					BUFM	ALTS	0000
AD1CON3	0324	ADRC	—	—	SAMC<4:0>					ADCS<7:0>								0000
AD1CHS123	0326	—	—	—	—	—	CH123NB<1:0>		CH123SB	—	—	—	—	—	CH123NA<1:0>		CH123SA	0000
AD1CHS0	0328	CH0NB	—	—	CH0SB<4:0>					CH0NA	—	—	CH0SA<4:0>					0000
AD1CSSH	032E	CSS31	CSS30	—	—	—	CSS26	CSS25	CSS24	—	—	—	—	—	—	—	—	0000
AD1CSSL	0330	CSS15	CSS14	CSS13	CSS12	CSS11	CSS10	CSS9	CSS8	CSS7	CSS6	CSS5	CSS4	CSS3	CSS2	CSS1	CSS0	0000
AD1CON4	0332	—	—	—	—	—	—	—	ADDMAEN	—	—	—	—	—	DMABL<2:0>			0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Allocating different Page registers for read and write access allows the architecture to support data movement between different pages in data memory. This is accomplished by setting the DSRPAG register value to the page from which you want to read, and configuring the DSWPAG register to the page to which it needs to be written. Data can also be moved from different PSV to EDS pages, by configuring the DSRPAG and DSWPAG registers to address PSV and EDS space, respectively. The data can be moved between pages by a single instruction.

When an EDS or PSV page overflow or underflow occurs, EA<15> is cleared as a result of the register indirect EA calculation. An overflow or underflow of the EA in the EDS or PSV pages can occur at the page boundaries when:

- The initial address prior to modification addresses an EDS or PSV page
- The EA calculation uses Pre-Modified or Post-Modified Register Indirect Addressing; however, this does not include Register Offset Addressing

In general, when an overflow is detected, the DSxPAG register is incremented and the EA<15> bit is set to keep the base address within the EDS or PSV window. When an underflow is detected, the DSxPAG register is decremented and the EA<15> bit is set to keep the base address within the EDS or PSV window. This creates a linear EDS and PSV address space, but only when using Register Indirect Addressing modes.

Exceptions to the operation described above arise when entering and exiting the boundaries of Page 0, EDS and PSV spaces. Table 4-61 lists the effects of overflow and underflow scenarios at different boundaries.

In the following cases, when overflow or underflow occurs, the EA<15> bit is set and the DSxPAG is not modified; therefore, the EA will wrap to the beginning of the current page:

- Register Indirect with Register Offset Addressing
- Modulo Addressing
- Bit-Reversed Addressing

TABLE 4-61: OVERFLOW AND UNDERFLOW SCENARIOS AT PAGE 0, EDS and PSV SPACE BOUNDARIES[2,3,4]

O/U, R/W	Operation	Before			After		
		DSxPAG	**DS EA<15>**	**Page Description**	**DSxPAG**	**DS EA<15>**	**Page Description**
O, Read	[++Wn] or [Wn++]	DSRPAG = 0x1FF	1	EDS: Last page	DSRPAG = 0x1FF	0	See **Note 1**
O, Read		DSRPAG = 0x2FF	1	PSV: Last lsw page	DSRPAG = 0x300	1	PSV: First MSB page
O, Read		DSRPAG = 0x3FF	1	PSV: Last MSB page	DSRPAG = 0x3FF	0	See **Note 1**
O, Write		DSWPAG = 0x1FF	1	EDS: Last page	DSWPAG = 0x1FF	0	See **Note 1**
U, Read	[--Wn] or [Wn--]	DSRPAG = 0x001	1	PSV page	DSRPAG = 0x001	0	See **Note 1**
U, Read		DSRPAG = 0x200	1	PSV: First lsw page	DSRPAG = 0x200	0	See **Note 1**
U, Read		DSRPAG = 0x300	1	PSV: First MSB page	DSRPAG = 0x2FF	1	PSV: Last lsw page

Legend: O = Overflow, U = Underflow, R = Read, W = Write

Note 1: The Register Indirect Addressing now addresses a location in the base Data Space (0x0000-0x8000).

2: An EDS access with DSxPAG = 0x000 will generate an address error trap.

3: Only reads from PS are supported using DSRPAG. An attempt to write to PS using DSWPAG will generate an address error trap.

4: Pseudo-Linear Addressing is not supported for large offsets.

4.5.3 MOVE AND ACCUMULATOR INSTRUCTIONS

Move instructions, which apply to dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices, and the DSP accumulator class of instructions, which apply to the dsPIC33EPXXXMC20X/50X and dsPIC33EPXXXGP50X devices, provide a greater degree of addressing flexibility than other instructions. In addition to the addressing modes supported by most MCU instructions, move and accumulator instructions also support Register Indirect with Register Offset Addressing mode, also referred to as Register Indexed mode.

> **Note:** For the MOV instructions, the addressing mode specified in the instruction can differ for the source and destination EA. However, the 4-bit Wb (Register Offset) field is shared by both source and destination (but typically only used by one).

In summary, the following addressing modes are supported by move and accumulator instructions:

- Register Direct
- Register Indirect
- Register Indirect Post-modified
- Register Indirect Pre-modified
- Register Indirect with Register Offset (Indexed)
- Register Indirect with Literal Offset
- 8-Bit Literal
- 16-Bit Literal

> **Note:** Not all instructions support all the addressing modes given above. Individual instructions may support different subsets of these addressing modes.

4.5.4 MAC INSTRUCTIONS (dsPIC33EPXXXMC20X/50X and dsPIC33EPXXXGP50X DEVICES ONLY)

The dual source operand DSP instructions (CLR, ED, EDAC, MAC, MPY, MPY.N, MOVSAC and MSC), also referred to as MAC instructions, use a simplified set of addressing modes to allow the user application to effectively manipulate the Data Pointers through register indirect tables.

The Two-Source Operand Prefetch registers must be members of the set: {W8, W9, W10, W11}. For data reads, W8 and W9 are always directed to the X RAGU, and W10 and W11 are always directed to the Y AGU. The Effective Addresses generated (before and after modification) must therefore, be valid addresses within X Data Space for W8 and W9, and Y Data Space for W10 and W11.

> **Note:** Register Indirect with Register Offset Addressing mode is available only for W9 (in X space) and W11 (in Y space).

In summary, the following addressing modes are supported by the MAC class of instructions:

- Register Indirect
- Register Indirect Post-Modified by 2
- Register Indirect Post-Modified by 4
- Register Indirect Post-Modified by 6
- Register Indirect with Register Offset (Indexed)

4.5.5 OTHER INSTRUCTIONS

Besides the addressing modes outlined previously, some instructions use literal constants of various sizes. For example, BRA (branch) instructions use 16-bit signed literals to specify the branch destination directly, whereas the DISI instruction uses a 14-bit unsigned literal field. In some instructions, such as ULNK, the source of an operand or result is implied by the opcode itself. Certain operations, such as a NOP, do not have any operands.

10.2.1 SLEEP MODE

The following occurs in Sleep mode:

- The system clock source is shut down. If an on-chip oscillator is used, it is turned off.
- The device current consumption is reduced to a minimum, provided that no I/O pin is sourcing current.
- The Fail-Safe Clock Monitor does not operate, since the system clock source is disabled.
- The LPRC clock continues to run in Sleep mode if the WDT is enabled.
- The WDT, if enabled, is automatically cleared prior to entering Sleep mode.
- Some device features or peripherals can continue to operate. This includes items such as the Input Change Notification (ICN) on the I/O ports or peripherals that use an external clock input.
- Any peripheral that requires the system clock source for its operation is disabled.

The device wakes up from Sleep mode on any of these events:

- Any interrupt source that is individually enabled
- Any form of device Reset
- A WDT time-out

On wake-up from Sleep mode, the processor restarts with the same clock source that was active when Sleep mode was entered.

For optimal power savings, the internal regulator and the Flash regulator can be configured to go into Standby when Sleep mode is entered by clearing the VREGS (RCON<8>) and VREGSF (RCON<11>) bits (default configuration).

If the application requires a faster wake-up time, and can accept higher current requirements, the VREGS (RCON<8>) and VREGSF (RCON<11>) bits can be set to keep the internal regulator and the Flash regulator active during Sleep mode.

10.2.2 IDLE MODE

The following occurs in Idle mode:

- The CPU stops executing instructions.
- The WDT is automatically cleared.
- The system clock source remains active. By default, all peripheral modules continue to operate normally from the system clock source, but can also be selectively disabled (see **Section 10.4 "Peripheral Module Disable"**).
- If the WDT or FSCM is enabled, the LPRC also remains active.

The device wakes from Idle mode on any of these events:

- Any interrupt that is individually enabled
- Any device Reset
- A WDT time-out

On wake-up from Idle mode, the clock is reapplied to the CPU and instruction execution will begin (2-4 clock cycles later), starting with the instruction following the PWRSAV instruction or the first instruction in the Interrupt Service Routine (ISR).

All peripherals also have the option to discontinue operation when Idle mode is entered to allow for increased power savings. This option is selectable in the control register of each peripheral; for example, the TSIDL bit in the Timer1 Control register (T1CON<13>).

10.2.3 INTERRUPTS COINCIDENT WITH POWER SAVE INSTRUCTIONS

Any interrupt that coincides with the execution of a PWRSAV instruction is held off until entry into Sleep or Idle mode has completed. The device then wakes up from Sleep or Idle mode.

12.0 TIMER1

> **Note 1:** This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"Timers"** (DS70362) in the "*dsPIC33/PIC24 Family Reference Manual*", which is available from the Microchip web site (www.microchip.com).
>
> **2:** Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The Timer1 module is a 16-bit timer that can operate as a free-running interval timer/counter.

The Timer1 module has the following unique features over other timers:

- Can be operated in Asynchronous Counter mode from an external clock source
- The external clock input (T1CK) can optionally be synchronized to the internal device clock and the clock synchronization is performed after the prescaler

A block diagram of Timer1 is shown in Figure 12-1.

The Timer1 module can operate in one of the following modes:

- Timer mode
- Gated Timer mode
- Synchronous Counter mode
- Asynchronous Counter mode

In Timer and Gated Timer modes, the input clock is derived from the internal instruction cycle clock (F_{CY}). In Synchronous and Asynchronous Counter modes, the input clock is derived from the external clock input at the T1CK pin.

The Timer modes are determined by the following bits:

- Timer Clock Source Control bit (TCS): T1CON<1>
- Timer Synchronization Control bit (TSYNC): T1CON<2>
- Timer Gate Control bit (TGATE): T1CON<6>

Timer control bit setting for different operating modes are given in the Table 12-1.

TABLE 12-1: TIMER MODE SETTINGS

Mode	TCS	TGATE	TSYNC
Timer	0	0	x
Gated Timer	0	1	x
Synchronous Counter	1	x	1
Asynchronous Counter	1	x	0

FIGURE 12-1: 16-BIT TIMER1 MODULE BLOCK DIAGRAM

Note 1: F_P is the peripheral clock.
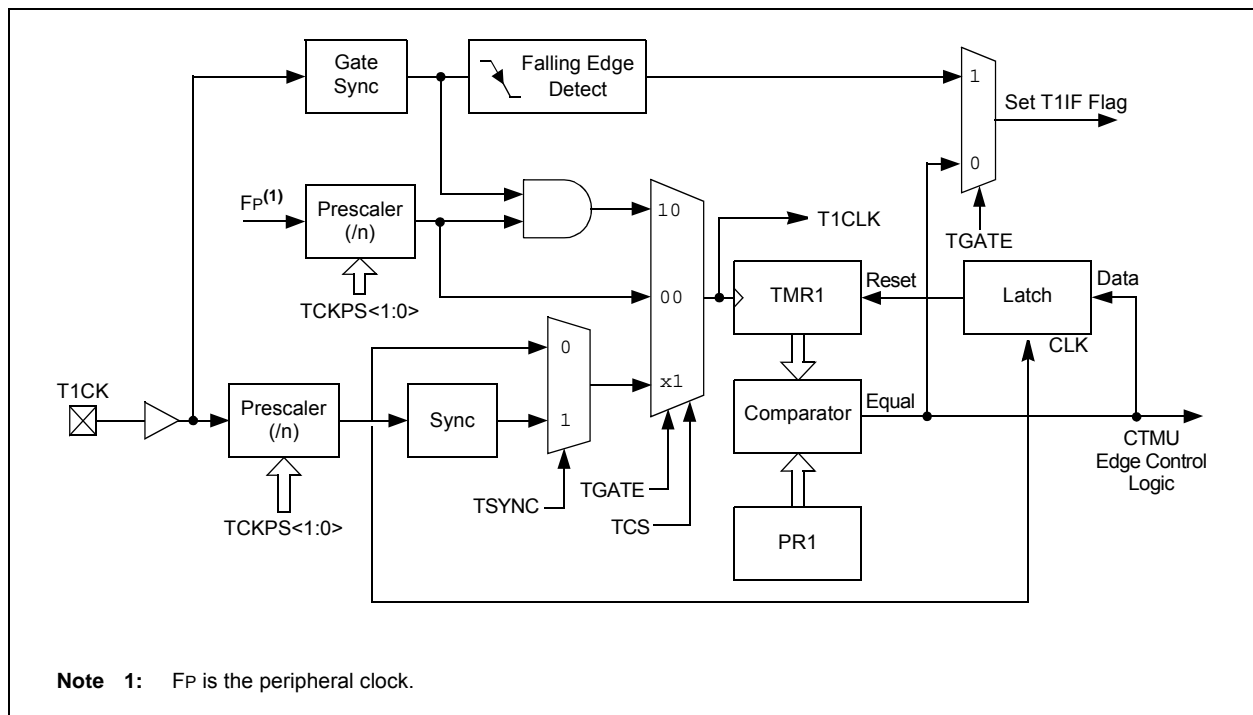
22.0 CHARGE TIME MEASUREMENT UNIT (CTMU)

> **Note 1:** This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"Charge Time Measurement Unit (CTMU)"** (DS70661) in the "*dsPIC33/PIC24 Family Reference Manual"*, which is available on the Microchip web site (www.microchip.com).
>
> **2:** Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The Charge Time Measurement Unit is a flexible analog module that provides accurate differential time measurement between pulse sources, as well as asynchronous pulse generation. Its key features include:

- Four Edge Input Trigger Sources
- Polarity Control for Each Edge Source
- Control of Edge Sequence
- Control of Response to Edges
- Precise Time Measurement Resolution of 1 ns
- Accurate Current Source Suitable for Capacitive Measurement
- On-Chip Temperature Measurement using a Built-in Diode

Together with other on-chip analog modules, the CTMU can be used to precisely measure time, measure capacitance, measure relative changes in capacitance or generate output pulses that are independent of the system clock.

The CTMU module is ideal for interfacing with capacitive-based sensors.The CTMU is controlled through three registers: CTMUCON1, CTMUCON2 and CTMUICON. CTMUCON1 and CTMUCON2 enable the module and control edge source selection, edge source polarity selection and edge sequencing. The CTMUICON register controls the selection and trim of the current source.

TABLE 30-4: DC TEMPERATURE AND VOLTAGE SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions (see Note 1): 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	Symbol	Characteristic	Min.	Typ.	Max.	Units	Conditions
Operating Voltage							
DC10	VDD	**Supply Voltage**	3.0	—	3.6	V	
DC16	VPOR	**VDD Start Voltage** to Ensure Internal Power-on Reset Signal	—	—	VSS	V	
DC17	SVDD	**VDD Rise Rate** to Ensure Internal Power-on Reset Signal	0.03	—	—	V/ms	0V-1V in 100 ms

Note 1: Device is functional at VBORMIN < VDD < VDDMIN. Analog modules (ADC, op amp/comparator and comparator voltage reference) may have degraded performance. Device functionality is tested but not characterized. Refer to Parameter BO10 in Table 30-13 for the minimum and maximum BOR values.

TABLE 30-5: FILTER CAPACITOR (CEFC) SPECIFICATIONS

Standard Operating Conditions (unless otherwise stated): Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended							
Param No.	Symbol	Characteristics	Min.	Typ.	Max.	Units	Comments
	CEFC	External Filter Capacitor Value[1]	4.7	10	—	µF	Capacitor must have a low series resistance (< 1 Ohm)

Note 1: Typical VCAP voltage = 1.8 volts when VDD ≥ VDDMIN.

TABLE 30-8: DC CHARACTERISTICS: POWER-DOWN CURRENT (IPD)

DC CHARACTERISTICS				Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended	
Parameter No.	Typ.	Max.	Units	Conditions	
Power-Down Current (IPD)[1] – dsPIC33EP32GP50X, dsPIC33EP32MC20X/50X and PIC24EP32GP/MC20X					
DC60d	30	100	μA	-40°C	3.3V
DC60a	35	100	μA	+25°C	
DC60b	150	200	μA	+85°C	
DC60c	250	500	μA	+125°C	
Power-Down Current (IPD)[1] – dsPIC33EP64GP50X, dsPIC33EP64MC20X/50X and PIC24EP64GP/MC20X					
DC60d	25	100	μA	-40°C	3.3V
DC60a	30	100	μA	+25°C	
DC60b	150	350	μA	+85°C	
DC60c	350	800	μA	+125°C	
Power-Down Current (IPD)[1] – dsPIC33EP128GP50X, dsPIC33EP128MC20X/50X and PIC24EP128GP/MC20X					
DC60d	30	100	μA	-40°C	3.3V
DC60a	35	100	μA	+25°C	
DC60b	150	350	μA	+85°C	
DC60c	550	1000	μA	+125°C	
Power-Down Current (IPD)[1] – dsPIC33EP256GP50X, dsPIC33EP256MC20X/50X and PIC24EP256GP/MC20X					
DC60d	35	100	μA	-40°C	3.3V
DC60a	40	100	μA	+25°C	
DC60b	250	450	μA	+85°C	
DC60c	1000	1200	μA	+125°C	
Power-Down Current (IPD)[1] – dsPIC33EP512GP50X, dsPIC33EP512MC20X/50X and PIC24EP512GP/MC20X					
DC60d	40	100	μA	-40°C	3.3V
DC60a	45	100	μA	+25°C	
DC60b	350	800	μA	+85°C	
DC60c	1100	1500	μA	+125°C	

Note 1: IPD (Sleep) current is measured as follows:

- CPU core is off, oscillator is configured in EC mode and external clock is active; OSC1 is driven with external square wave from rail-to-rail (EC clock overshoot/undershoot < 250 mV required)
- CLKO is configured as an I/O input pin in the Configuration Word
- All I/O pins are configured as inputs and pulled to VSS
- $\overline{MCLR}$ = VDD, WDT and FSCM are disabled
- All peripheral modules are disabled (PMDx bits are all set)
- The VREGS bit (RCON<8>) = 0 (i.e., core regulator is set to standby while the device is in Sleep mode)
- The VREGSF bit (RCON<11>) = 0 (i.e., Flash regulator is set to standby while the device is in Sleep mode)
- JTAG is disabled

FIGURE 30-5: **TIMER1-TIMER5 EXTERNAL CLOCK TIMING CHARACTERISTICS**

Note: Refer to Figure 30-1 for load conditions.
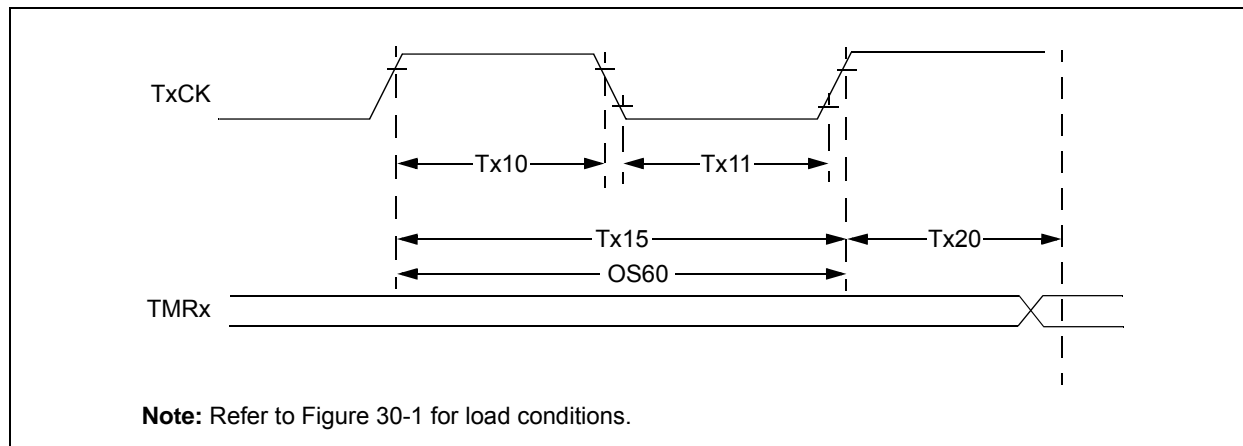
TABLE 30-23: **TIMER1 EXTERNAL CLOCK TIMING REQUIREMENTS[1]**

AC CHARACTERISTICS				Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	Symbol	Characteristic[2]		Min.	Typ.	Max.	Units	Conditions
TA10	T$_{TxH}$	T1CK High Time	Synchronous mode	Greater of: 20 or (T$_{CY}$ + 20)/N	—	—	ns	Must also meet Parameter TA15, N = prescaler value (1, 8, 64, 256)
			Asynchronous	35	—	—	ns	
TA11	T$_{TxL}$	T1CK Low Time	Synchronous mode	Greater of: 20 or (T$_{CY}$ + 20)/N	—	—	ns	Must also meet Parameter TA15, N = prescaler value (1, 8, 64, 256)
			Asynchronous	10	—	—	ns	
TA15	T$_{TxP}$	T1CK Input Period	Synchronous mode	Greater of: 40 or (2 T$_{CY}$ + 40)/N	—	—	ns	N = prescale value (1, 8, 64, 256)
OS60	Ft1	T1CK Oscillator Input Frequency Range (oscillator enabled by setting bit, TCS (T1CON<1>))		DC	—	50	kHz	
TA20	T$_{CKEXTMRL}$	Delay from External T1CK Clock Edge to Timer Increment		0.75 T$_{CY}$ + 40	—	1.75 T$_{CY}$ + 40	ns	

Note 1: Timer1 is a Type A.

2: These parameters are characterized, but are not tested in manufacturing.

FIGURE 30-18: **SPI2 SLAVE MODE (FULL-DUPLEX, CKE = 1, CKP = 0, SMP = 0)**
TIMING CHARACTERISTICS
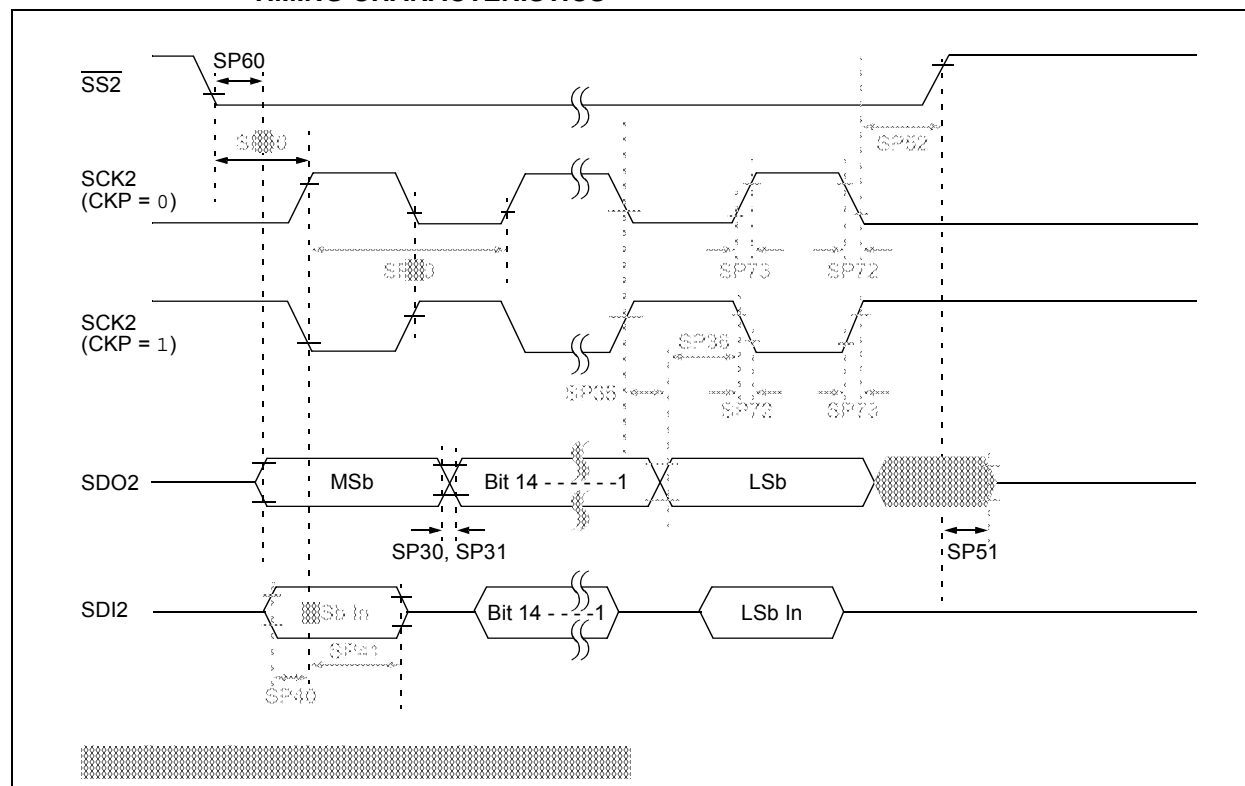
FIGURE 30-23: SPI1 MASTER MODE (HALF-DUPLEX, TRANSMIT ONLY, CKE = 1)
TIMING CHARACTERISTICS

Note: Refer to Figure 30-1 for load conditions.
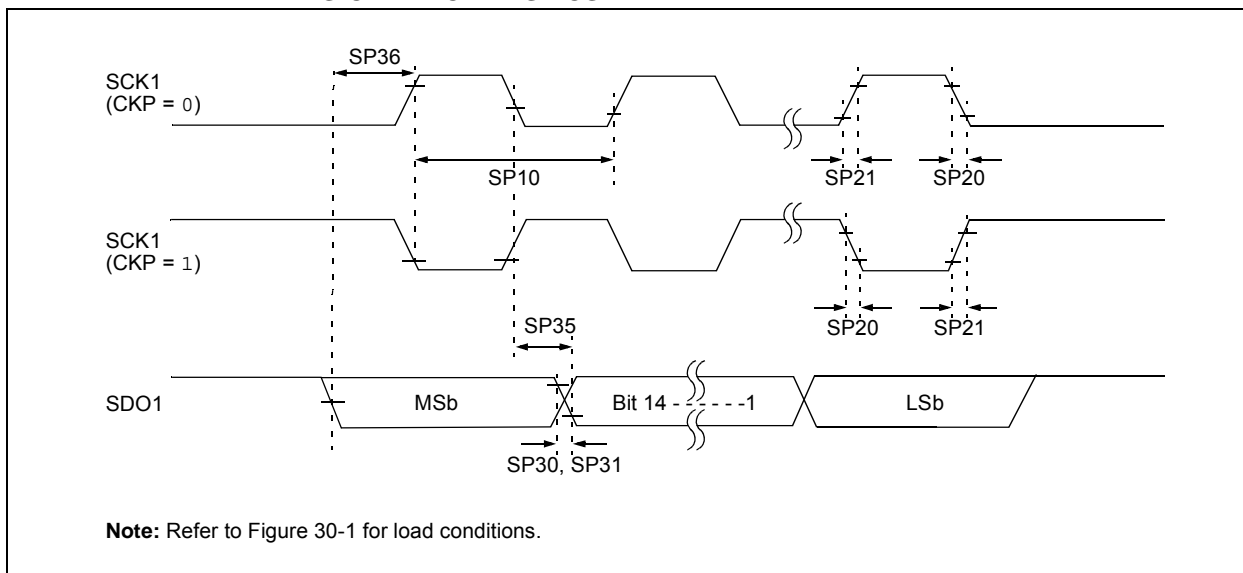
TABLE 30-42:   SPI1 MASTER MODE (HALF-DUPLEX, TRANSMIT ONLY) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	Symbol	Characteristic[1]	Min.	Typ.[2]	Max.	Units	Conditions
SP10	FscP	Maximum SCK1 Frequency	—	—	15	MHz	(Note 3)
SP20	TscF	SCK1 Output Fall Time	—	—	—	ns	See Parameter DO32 (Note 4)
SP21	TscR	SCK1 Output Rise Time	—	—	—	ns	See Parameter DO31 (Note 4)
SP30	TdoF	SDO1 Data Output Fall Time	—	—	—	ns	See Parameter DO32 (Note 4)
SP31	TdoR	SDO1 Data Output Rise Time	—	—	—	ns	See Parameter DO31 (Note 4)
SP35	TscH2doV, TscL2doV	SDO1 Data Output Valid after SCK1 Edge	—	6	20	ns	
SP36	TdiV2scH, TdiV2scL	SDO1 Data Output Setup to First SCK1 Edge	30	—	—	ns	

Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in "Typical" column is at 3.3V, +25°C unless otherwise stated.

3: The minimum clock period for SCK1 is 66.7 ns. Therefore, the clock generated in Master mode must not violate this specification.

4: Assumes 50 pF load on all SPI1 pins.

FIGURE 30-24: SPI1 MASTER MODE (FULL-DUPLEX, CKE = 1, CKP = x, SMP = 1)
TIMING CHARACTERISTICS

Note: Refer to Figure 30-1 for load conditions.
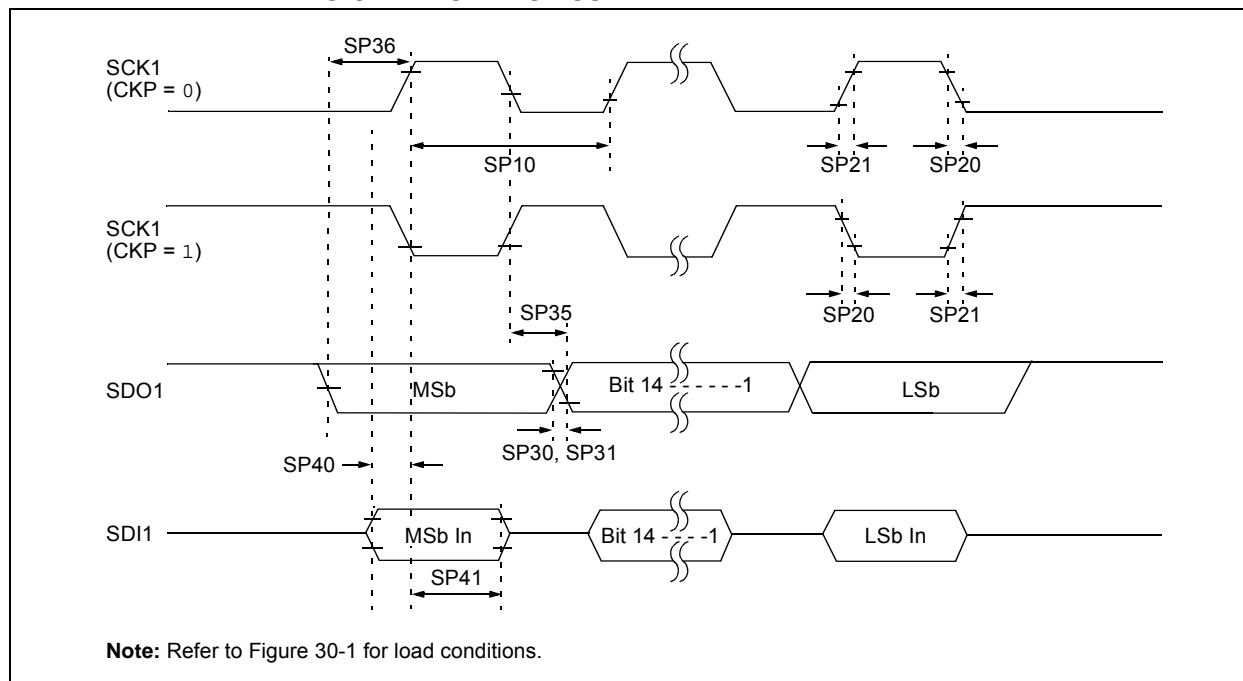
TABLE 30-43: SPI1 MASTER MODE (FULL-DUPLEX, CKE = 1, CKP = x, SMP = 1)
TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	Symbol	Characteristic[1]	Min.	Typ.[2]	Max.	Units	Conditions
SP10	FscP	Maximum SCK1 Frequency	—	—	10	MHz	(Note 3)
SP20	TscF	SCK1 Output Fall Time	—	—	—	ns	See Parameter DO32 (Note 4)
SP21	TscR	SCK1 Output Rise Time	—	—	—	ns	See Parameter DO31 (Note 4)
SP30	TdoF	SDO1 Data Output Fall Time	—	—	—	ns	See Parameter DO32 (Note 4)
SP31	TdoR	SDO1 Data Output Rise Time	—	—	—	ns	See Parameter DO31 (Note 4)
SP35	TscH2doV, TscL2doV	SDO1 Data Output Valid after SCK1 Edge	—	6	20	ns	
SP36	TdoV2sc, TdoV2scL	SDO1 Data Output Setup to First SCK1 Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDI1 Data Input to SCK1 Edge	30	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDI1 Data Input to SCK1 Edge	30	—	—	ns	

Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in "Typical" column is at 3.3V, +25°C unless otherwise stated.

3: The minimum clock period for SCK1 is 100 ns. The clock generated in Master mode must not violate this specification.

4: Assumes 50 pF load on all SPI1 pins.

TABLE 30-47: SPI1 SLAVE MODE (FULL-DUPLEX, CKE = 0, CKP = 1, SMP = 0)
TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	Symbol	Characteristic[1]	Min.	Typ.[2]	Max.	Units	Conditions
SP70	FscP	Maximum SCK1 Input Frequency	—	—	15	MHz	**(Note 3)**
SP72	TscF	SCK1 Input Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP73	TscR	SCK1 Input Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP30	TdoF	SDO1 Data Output Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP31	TdoR	SDO1 Data Output Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP35	TscH2doV, TscL2doV	SDO1 Data Output Valid after SCK1 Edge	—	6	20	ns	
SP36	TdoV2scH, TdoV2scL	SDO1 Data Output Setup to First SCK1 Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDI1 Data Input to SCK1 Edge	30	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDI1 Data Input to SCK1 Edge	30	—	—	ns	
SP50	TssL2scH, TssL2scL	$\overline{SS1}$ ↓ to SCK1 ↑ or SCK1 ↓ Input	120	—	—	ns	
SP51	TssH2doZ	$\overline{SS1}$ ↑ to SDO1 Output High-Impedance	10	—	50	ns	**(Note 4)**
SP52	TscH2ssH, TscL2ssH	$\overline{SS1}$ ↑ after SCK1 Edge	1.5 TCY + 40	—	—	ns	**(Note 4)**

Note 1: These parameters are characterized, but are not tested in manufacturing.

   2: Data in "Typical" column is at 3.3V, +25°C unless otherwise stated.

   3: The minimum clock period for SCK1 is 66.7 ns. Therefore, the SCK1 clock generated by the master must not violate this specification.

   4: Assumes 50 pF load on all SPI1 pins.

TABLE 30-53: OP AMP/COMPARATOR SPECIFICATIONS (CONTINUED)

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)[1] Operating temperature -40°C $\leq$ TA $\leq$ +85°C for Industrial -40°C $\leq$ TA $\leq$ +125°C for Extended				
Param No.	Symbol	Characteristic	Min.	Typ.[2]	Max.	Units	Conditions
Op Amp DC Characteristics							
CM40	VCMR	Common-Mode Input Voltage Range	AVSS	—	AVDD	V	
CM41	CMRR	Common-Mode Rejection Ratio[3]	—	40	—	db	VCM = AVDD/2
CM42	VOFFSET	Op Amp Offset Voltage[3]	—	±5	—	mV	
CM43	VGAIN	Open-Loop Voltage Gain[3]	—	90	—	db	
CM44	IOS	Input Offset Current	—	—	—	—	See pad leakage currents in Table 30-11
CM45	IB	Input Bias Current	—	—	—	—	See pad leakage currents in Table 30-11
CM46	IOUT	Output Current	—	—	420	µA	With minimum value of RFEEDBACK (CM48)
CM48	RFEEDBACK	Feedback Resistance Value	8	—	—	kΩ	
CM49a	VOADC	Output Voltage Measured at OAx Using ADC[3,4]	AVSS + 0.077 AVSS + 0.037 AVSS + 0.018	— — —	AVDD – 0.077 AVDD – 0.037 AVDD – 0.018	V V V	IOUT = 420 µA IOUT = 200 µA IOUT = 100 µA
CM49b	VOUT	Output Voltage Measured at OAxOUT Pin[3,4,5]	AVSS + 0.210 AVSS + 0.100 AVSS + 0.050	— — —	AVDD – 0.210 AVDD – 0.100 AVDD – 0.050	V V V	IOUT = 420 µA IOUT = 200 µA IOUT = 100 µA
CM51	RINT1[6]	Internal Resistance 1 (Configuration A and B)[3,4,5]	198	264	317	Ω	Min = -40ºC Typ = +25ºC Max = +125ºC

Note 1: Device is functional at VBORMIN < VDD < VDDMIN, but will have degraded performance. Device functionality is tested, but not characterized. Analog modules (ADC, op amp/comparator and comparator voltage reference) may have degraded performance. Refer to Parameter BO10 in Table 30-13 for the minimum and maximum BOR values.

2: Data in "Typ" column is at 3.3V, +25°C unless otherwise stated.

3: Parameter is characterized but not tested in manufacturing.

4: See Figure 25-6 for configuration information.

5: See Figure 25-7 for configuration information.

6: Resistances can vary by ±10% between op amps.